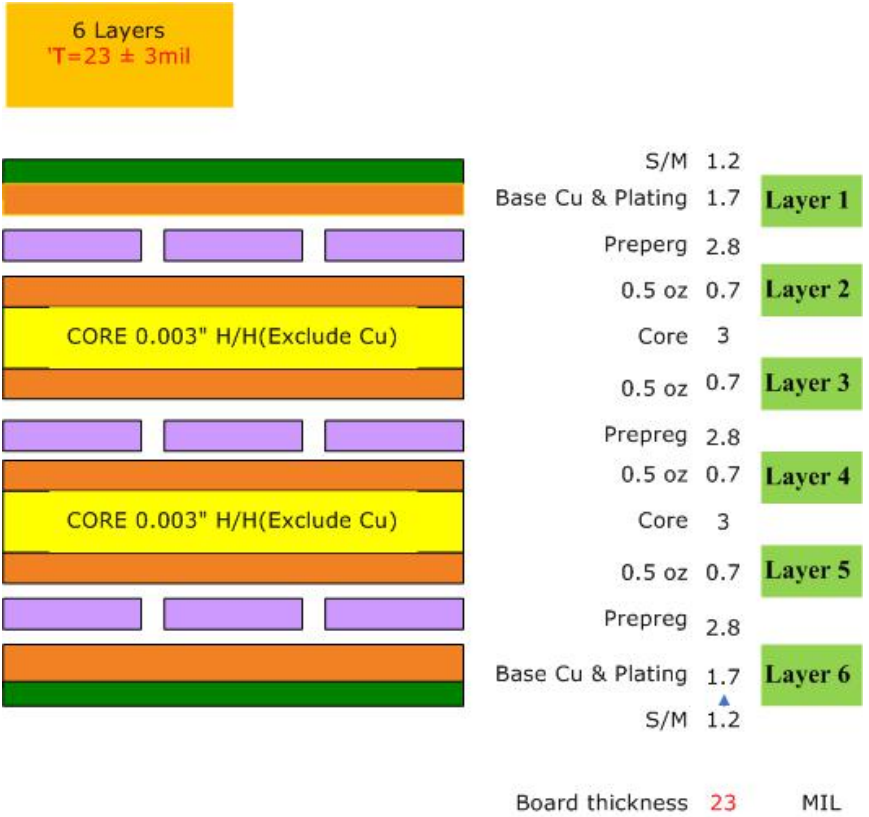


Layer stack up constructions:

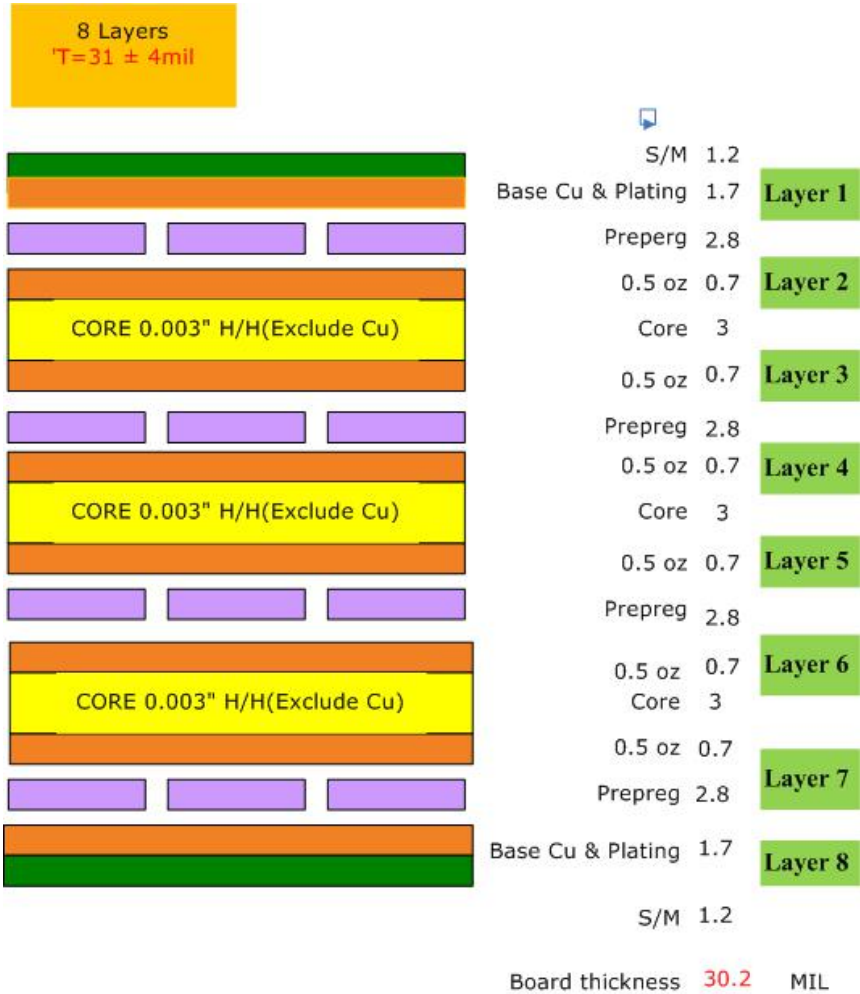
PCB stack up-4Layer



PCB stack up-6Layer



PCB stack up-8Layer



PCB stack up-10Layer

10 Layers
T=41 ± 4mil

	S/M	1.2	
	Base Cu & Plating	1.7	Layer 1
	Prepreg	2.8	
	0.5 oz	0.7	Layer 2
	Core	4	
	0.5 oz	0.7	Layer 3
	Prepreg	2.8	
	0.5 oz	0.7	Layer 4
	Core	4	
	0.5 oz	0.7	Layer 5
	Prepreg	2.8	
	0.5 oz	0.7	Layer 6
	Core	4	
	0.5 oz	0.7	Layer 7
	Prepreg	2.8	
	0.5 oz	0.7	Layer 8
	Core	4	
	0.5 oz	0.7	Layer 9
	Prepreg	2.8	
	Base Cu & Plating	1.7	Layer 10
	S/M	1.2	
Board thickness 41.4 MIL			

PCB stack up-12Layer

12= Layers
T=50 ± 5mil

	S/M	1.2	
	Base Cu & Plating	1.7	Layer 1
	Prepreg	2.8	
	0.5 oz	0.7	Layer 2
	Core	4	
	0.5 oz	0.7	Layer 3
	Prepreg	2.8	
	0.5 oz	0.7	Layer 4
	Core	4	
	0.5 oz	0.7	Layer 5
	Prepreg	2.8	
	0.5 oz	0.7	Layer 6
	Core	4	
	0.5 oz	0.7	Layer 7
	Prepreg	2.8	
	0.5 oz	0.7	Layer 8
	Core	4	
	0.5 oz	0.7	Layer 9
	Prepreg	2.8	
	0.5 oz	0.7	Layer 10
	Core	4	
	0.5 oz	0.7	Layer 11
	Prepreg	2.8	
	Base Cu & Plating	1.7	Layer 12
	S/M	1.2	
Board thickness 49.6 MIL			